

WHAT IS CLAIMED IS:

1. A composition for forming a piezoelectric film comprising a dispersoid obtained from a metal compound, wherein the total content of the elemental
5 halogens, halogen ions and halogen compounds contained in said composition is 10 ppm or less.
2. A composition for forming piezoelectric film according to claim 1, wherein said metal
10 compound is an organometallic compound.
3. A composition for forming piezoelectric film according to claim 1, wherein the total content of the elemental halogens, halogen ions and halogen
15 compounds contained in said composition is 3 ppm or less.
4. A composition for forming piezoelectric film according to claim 1, wherein at least titanium,
20 zirconium and lead are contained as said metal.
5. A manufacturing method of piezoelectric film, comprising:
a process for forming a coating film by
25 applying onto a substrate said composition for forming piezoelectric film in which the total content of the elemental halogens, halogen ions and halogen

compounds contained in the composition comprising the dispersoid obtained from the metal compound is 10 ppm or less;

a process for drying said coating film; and

5 a process for obtaining a piezoelectric film by baking said dried coating film.

6. A piezoelectric element comprising a piezoelectric film sandwiched between a lower
10 electrode and an upper electrode, wherein said piezoelectric film is produced by the method according to claim 5.

7. A piezoelectric element according to claim
15 6, wherein the total content of the elemental halogens, halogen ions and halogen compounds contained in said piezoelectric film is 10 ppm or less.

20 8. An ink jet recording head, comprising a pressure chamber communicating with an ink jet orifice, a vibrating plate arranged in a manner corresponding to said pressure chamber, a piezoelectric element according to claim 6 arranged
25 in a manner corresponding to said vibrating plate, wherein the ink in said pressure chamber is jetted from said ink jet orifice owing to the volume change

within said pressure chamber caused by said piezoelectric element.